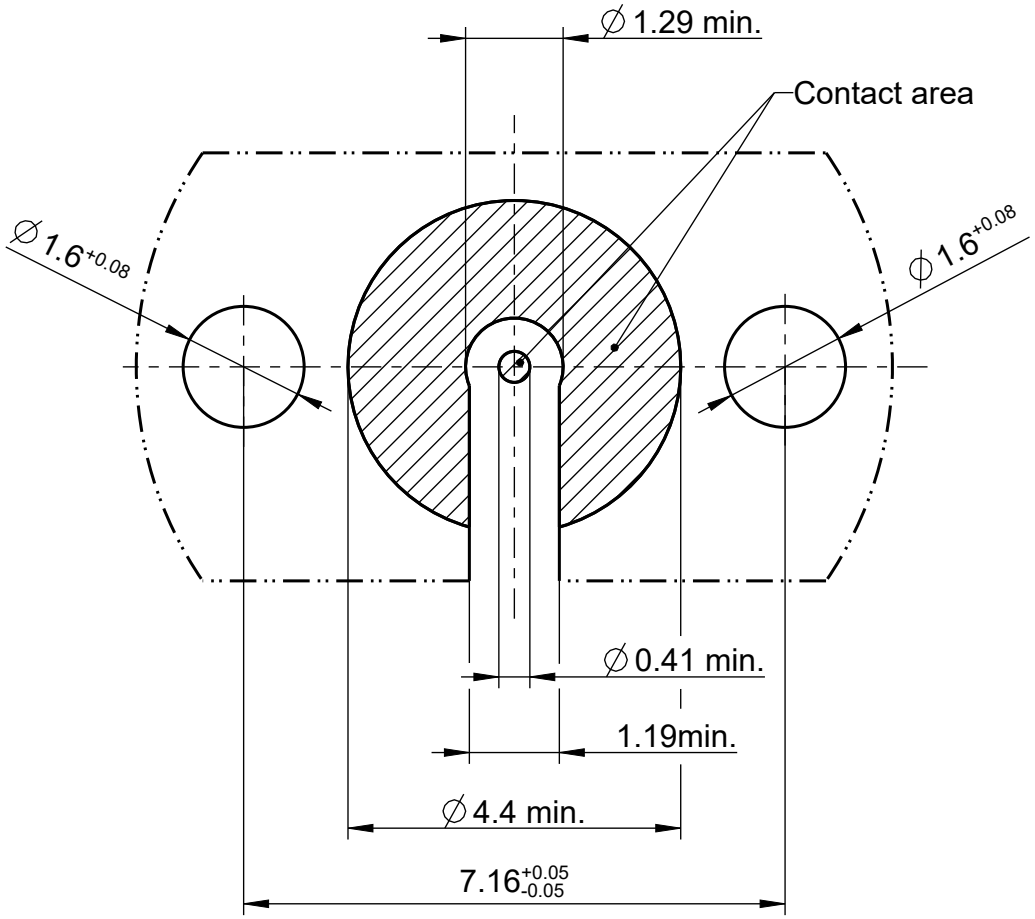
Leiterplatten-Layout
PCB layout
B 594F



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Die angegebenen Masse und Toleranzen sind nur Empfehlungen.
The stated dimensions are only recommendations.

Rosenberger	general tolerance: ISO 2768 mH	assembly instr.: --- / panel piercing: --	scale: 10:1 (1:1) / series: --- / ---
			crimp insert: --- / cable: --- / ---

vertraulich / *confidential*

	date	name
drawn	23.10.2018	M_Ruf
check.	28.11.2019	M_Rahberger
appr.	28.11.2019	M_Moder

title: Leiterplatten-Layout *PCB layout*

rev.	change-no	name	date
a00	19-s300	A_Youmsi-Mou	27.11.2019
100	18-v696	M_Ruf	23.10.2018

drawing-no.: MB_594F
sheet: 1
of: 1
remarks: .

PD_FB_01
-METRIC-
ISO-Projektion Methode 1